



## Materials Declaration Form

<b>IPC Form Type *</b>	<b>1752</b> Distribute	<b>Version</b>	<b>2</b>
<b>Sectionals *</b>	<b>Material Info</b> Manufacturing Info	<b>Subsectionals *</b>	<b>A-D</b>
<b>* : Required Field</b>			

Supplier Information			
<b>Company Name *</b>	<b>STMicroelectronics</b>	<b>Response Date *</b>	<b>21/03/2013</b>
<b>Contact Name *</b>	Refer to "Supplier Comment" section	<b>Contact Title</b>	Refer to "Supplier Comment" section
<b>Contact Phone *</b>	Refer to "Supplier Comment" section	<b>Contact Email *</b>	Refer to "Supplier Comment" section
<b>Authorized Representative *</b>	Arcidiacono Salvatore	<b>Representative Title</b>	APM/IPD Materials Declaration Champion)
<b>Representative Phone *</b>	Refer to "Supplier Comment" section	<b>Representative Email *</b>	Refer to "Supplier Comment" section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/internet/com/support/online_tech_support.jsp">http://www.st.com/internet/com/support/online_tech_support.jsp</a>		

**Uncertainty Statement**

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**Legal Statement**

<b>Supplier Acceptance *</b>	<b>true</b>	<b>Legal Declaration *</b>	<b>Standard</b>
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**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
ST1S50PUR	MYWQ*UI78AC5	A	Z6HA	21/03/2013
	Amount	UoM	Unit type	ST ECOPACK Grade
	17.10	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFN	3 X 3 X 0.65	10	No lead	
Comment				

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList :REACH-19 December 2012				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	MYWQ*UI78AC5					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
die (s)	Other inorganic materials	1.54	mg	supplier	die	Silicon (Si)	7440-21-3		1.523	mg	988961	89064
die (s)				supplier	back side metallization	Chromium (Cr)	7440-47-3		0.001	mg	649	58
die (s)				supplier	back side metallization	Gold (Au)	7440-57-5		0.004	mg	2597	234
die (s)				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.011	mg	7143	643
die (s)				supplier	back side metallization	Vanadium (V)	7440-62-2		0.001	mg	649	58
Leadframe	Copper & its alloys	10.62	mg	supplier	alloy	Copper (Cu)	7440-50-8		10.295	mg	969397	602047
Leadframe				supplier	alloy	Iron (Fe)	7439-89-6		0.242	mg	22787	14152
Leadframe				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.015	mg	1412	877
Leadframe				supplier	alloy	Zinc (Zn)	7440-66-6		0.013	mg	1224	760
Leadframe				supplier	metallization	Silver (Ag)	7440-22-4		0.055	mg	5179	3216
Die attach	Other inorganic materials	0.545	mg	supplier	glue or tape	Silver (Ag)	7440-22-4		0.373	mg	684404	21813
Die attach				supplier	glue or tape	methylene diacrylate	42594-17-2		0.136	mg	249541	7953
Die attach				supplier	glue or tape	Dicyclopentenylmethacrylate	68586-19-6		0.016	mg	29358	936
Die attach				supplier	glue or tape	Polymer of Polybutadiene + Anhydride	Proprietary		0.016	mg	29358	936
Die attach				supplier	glue or tape	Palladium (Pd)	7440-05-3		0.001	mg	1835	58
Die attach				supplier	glue or tape	Bis(alpha,dimethylbenzyl) peroxide	80-43-3		0.003	mg	5505	175
Bonding wire	Other inorganic materials	0.234	mg	supplier	wire	Gold (Au)	7440-57-5		0.234	mg	1000000	13684
encapsulation	Other inorganic materials	4.161	mg	supplier	mold compound	Silica, vitreous	60676-86-0		3.853	mg	925979	225322
encapsulation				supplier	mold compound	epoxy resin	85954-11-6		0.166	mg	39894	9708
encapsulation				supplier	mold compound	phenol resin	26834-02-6		0.125	mg	30041	7310
encapsulation				supplier	mold compound	carbon black	1333-86-4		0.017	mg	4086	994